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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10052143	01/17/2002	257	789	2827	ZARNEKE

**APPLICANTS: Honda Hirokazu;

**CONTINUING DATA VERIFIED:

THIS APPLICATION IS A DIV OF 09/712,105 11/14/2000

** FOREIGN APPLICATIONS VERIFIED:

JAPAN 325770/1999 11/16/1999

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no

35 USC 119 conditions met ☐ yes ☐ no

Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

NEC 00USFP553 DIV

TITLE : Semiconductor device and manufacturing method the same

U.S. DEPT. OF COMM /PAT & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
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